AN ABSTRACT PROCESSING A GATE PORTION IN A SEMICONDUCTOR MANUFACTURING APPARATUS, WHICH REMOVES A GATE CORRESPONDENCE PORTION FROM A SEMICONDUCTOR PACKAGE CONNECTED TO A LEAD FRAME, AND A RESIN BURR DEPOSITED ON A LEAD PORTION ASSOCIATED WITH THE SEMICONDUCTOR PACKAGE

ABSTRACT

An apparatus processing a gate portion in a semiconductor manufacturing apparatus includes a laser beam scanner unit (1) and a cutter (14). The laser beam scanner unit (1) is disposed along a carrying line on which a lead frame (2) is carried. The laser beam scanner unit (1) has an optical scanner unit second-dimensionally scanning laser beams, and a lens unit collecting the laser beams (11). The cutter (14) has a punch (16). The punch (16) mechanically pushes to cut a gate correspondence portion (23) which is perfectly cut away or almost cut away from a semiconductor package body (22) by the laser beams (11).

Fig 6